

AMENDMENTS TO THE SPECIFICATION

Page 5, paragraph 5 has been amended to read:

In carrying out the method, wafer 1 is first glued with its front side having components 2 (an active side) to carrier substrate 4. The carrier substrate used can be e.g. another wafer, a metal foil or magnetizable foil or another kind of foil usual in smart card production such as PVC, ABS, PC or the like.

Page 6, paragraph 2 has been amended to read:

Figs 3a and 3b show an alternative method by which the active surface (front side) with components 2 of chips 10 ultimately lies on top. For this purpose, carrier film 5 is mounted on thinned and sawed wafer 1 by means of second adhesive layer 6. Said carrier film 5 can of course also be a self-adhesive foil already provided with an adhesive layer.